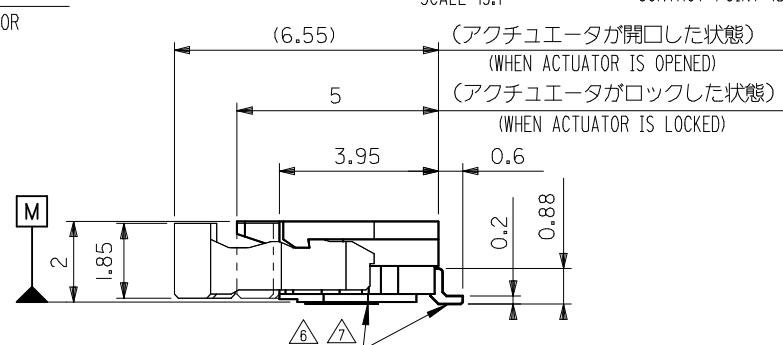
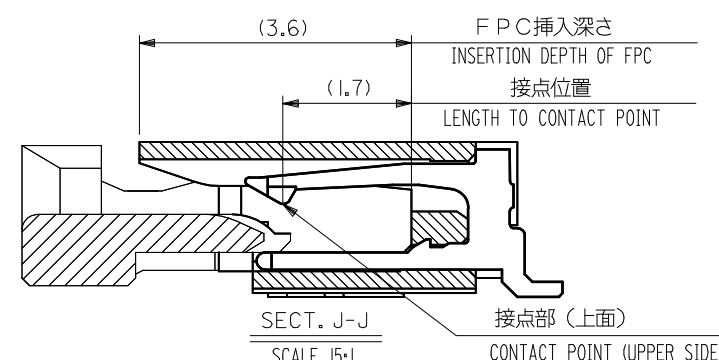
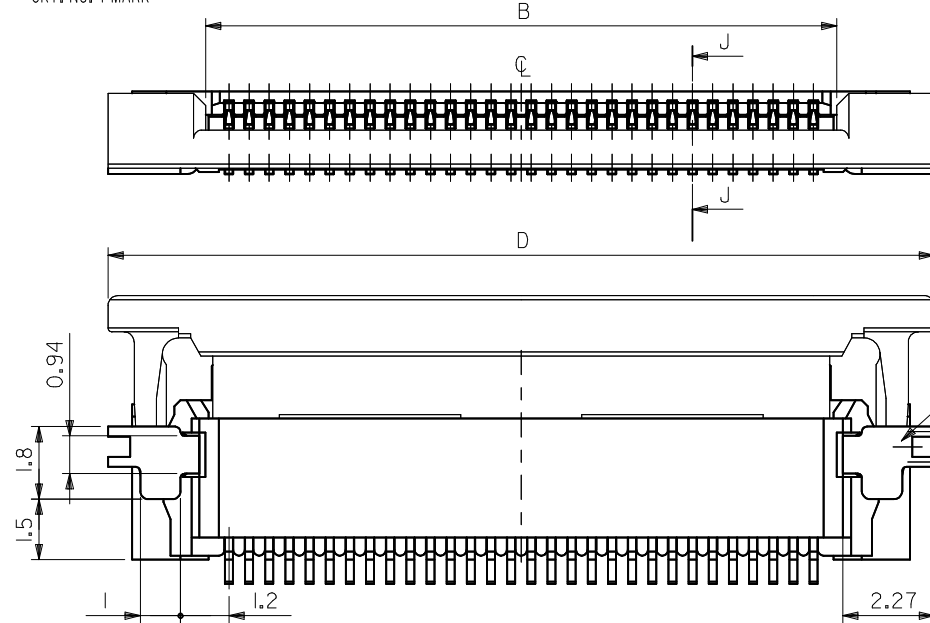
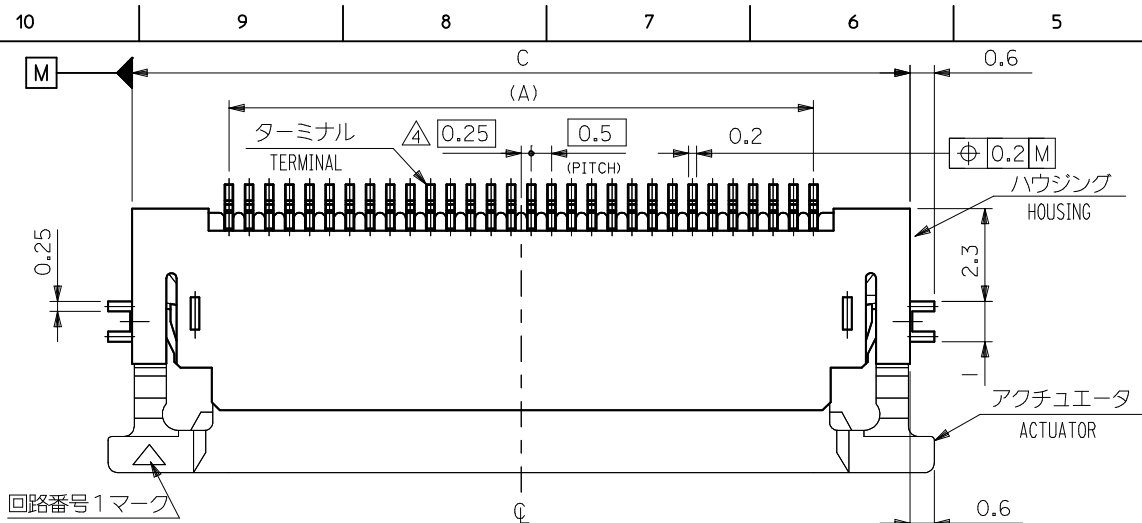




30.5	29.3	25.65	24.5	54104-5033	50
28.5	27.3	23.65	22.5	54104-4633	46
28.0	26.8	23.15	22.0	54104-4533	45
25.5	24.3	20.65	19.5	54104-4033	40
24.5	23.3	19.65	18.5	54104-3833	38
23.5	22.3	18.65	17.5	54104-3633	36
23.0	21.8	18.15	17.0	54104-3533	35
22.5	21.3	17.65	16.5	54104-3433	34
22.0	20.8	17.15	16.0	54104-3333	33
21.5	20.3	16.65	15.5	54104-3233	32
20.5	19.3	15.65	14.5	54104-3033	30
D	C	B	A	オーダー番号 ORDER NO.	CKT.

CONNECTOR SERIES NO. 54104-**22

REVISED EC NO: J2014-1557 DRW: AISHI CHKD: TAKAHASHI APPR: YNOGAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY KNAGUMO	DATE 2012/09/03	TITLE 0.5MM FPC CONN ZIF R/A HOUSING ASSY (UPPER CONTACT) molex				
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/06					
		30 OVER	± 0.3	APPROVED BY KMORI KAWA	DATE 2013/03/15					
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54104-083		1 OF 2			
REV		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

F

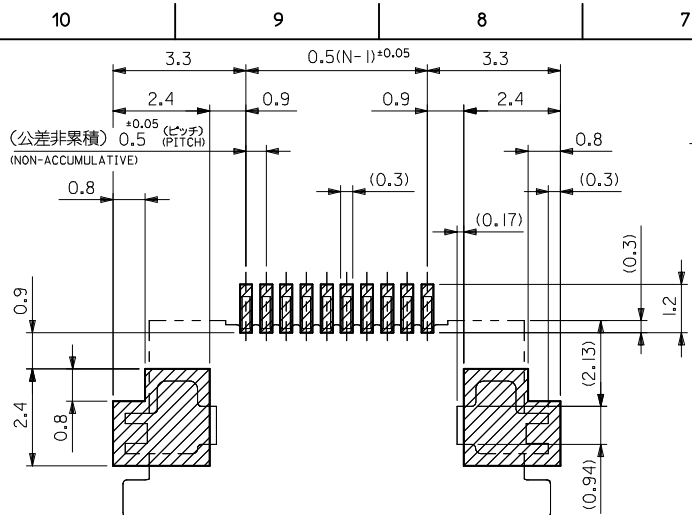
E

D

C

B

A



推奨基板レイアウト
RECOMMENDED P.C.BOARD
PATTERN DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)
マスク厚 : 100 μm
マスク開口率 : 100%
SCREEN THICKNESS : 100 MICROMETER
SCREEN OPEN RATIO: 100%

注記 NOTES

1. 材質 MATERIAL

ハウジング: ポリアミド (PPS), ガラス充填, ナチュラル(白色), UL94V-0
HOUSING: POLYAMIDE, GLASS FILLED, NATURAL(WHITE), UL94V-0
アクチュエータ: ポリフェニレンサルファイド, ガラス充填, ナチュラル(茶色), UL94V-0
ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, NATURAL(BROWN), UL94V-0
ターミナル: リン青銅 (t = 0.20)
TERMINAL: PHOSPHER BRONZE (t = 0.20)
金具: リン青銅 (t = 0.2)
NAIL : PHOSPHER BRONZE (t = 0.2)

2. メッキ仕様 PLATING

ターミナル TERMINAL
鍍銀ビスマスメッキ(1.0 μm以上)
TIN SILVER BISMUTH PLATING(1.0 MICROMETER MINIMUM)
下地メッキ: ニッケルメッキ(1.0 μm以上)
UNDER PLATING : NICKEL PLATING(1.0 MICROMETER MINIMUM)
金具
NAIL
鍍メッキ(1.0 μm以上)
TIN PLATING(1.0 MICROMETER MINIMUM)
下地メッキ: ニッケルメッキ(1.0 μm以上)
UNDER PLATING : NICKEL PLATING(1.0 MICROMETER MINIMUM)

△ R0.3はFPCの導体部にかからないこと
R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

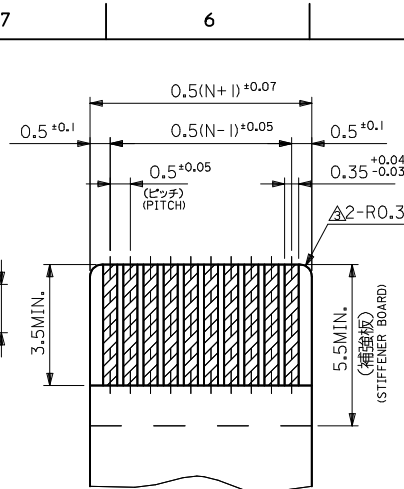
△ 偶数極に適用
APPLY FOR EVEN CIRCUIT

5. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR SHOULD BE LOCKED.
6. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 $\square$ に対し、
上方0.1MAX、下方0.15MAXとし、相互のバラツキ量は0.1MAXとする
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM $\square$ UPPER DIRECTION : 0.1MAX,
LOWER DIRECTION: 0.15MAX. OFFSET BETWEEN UPPER AND LOWER 0.1MAX

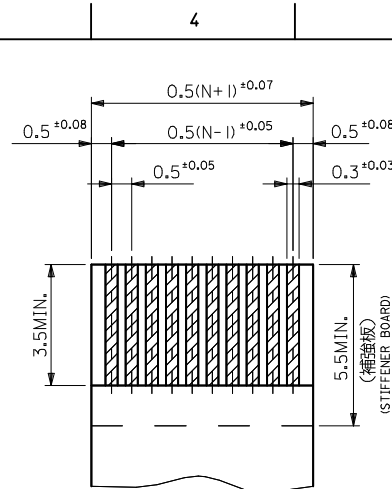
△ ソルダータール及び金具の平坦度は、0.1ミリメートル以下とする。
SOLDER TAIL AND FITTING NAIL COPLANARITY TO BE 0.1MILLIMETERS.

8. 本製品は54104シリーズの鍍銀ビスマスめっき品である。
THIS PRODUCT IS Sn-Ag-Bi PLATING OF 54104 SERIES.

9. ELV及びRoHS適合品
ELV & RoHS COMPLIANT



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

FPC/FFCについて ABOUT FPC/FFC

打ち抜き方向は導体側から補強板側を推奨します。

導体部については軟箔銅35 μmまたは50 μmを推奨します。

RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE

RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL

RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER

FPCについてABOUT FPC

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25 μmを推奨します。

接着剤は熱硬化接着剤を推奨します。

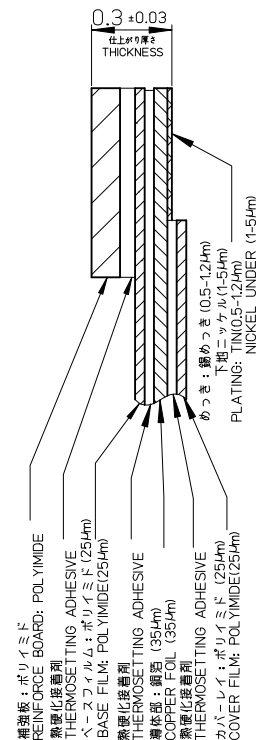
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

RECOMMENDED STIFFENER MATERIAL: POLYIMIDE

RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER

RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE

NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.



FPC構成推奨仕様
STRUCTURE OF FPC

SEE SHEET 1 OF 2 EC NO: J2014 -4557 DWG: AISHI CHK'D: K TAKAHASHI APPR: YNOGAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY KNAGUMO	DATE 2012/09/03	TITLE 0.5MM FPC CONN ZIF R/A HOUSING ASSY (UPPER CONTACT)			
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/06				
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15				
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.			SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54104-083			2 OF 2
		REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

F

E

D

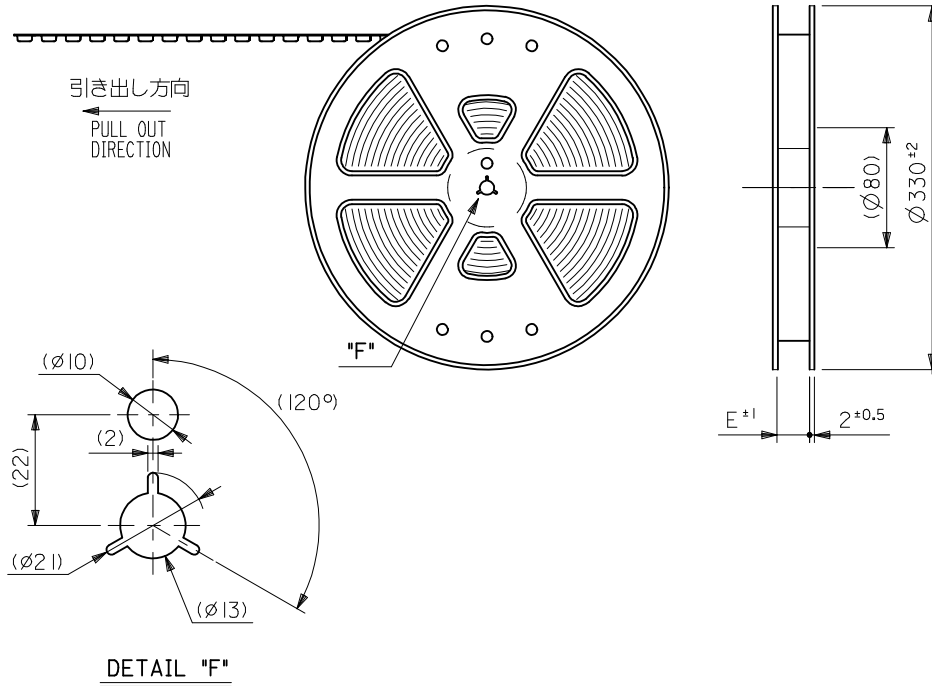
C

B

A

NOTES

- 製品番号54104-**-22の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については図面SD-54104-083を参照下さい。
IN THE PACKAGE, ACTUATOR OF PART NO.54104-**-22 SHOULD BE LOCKED
DETAIL DIMENSIONS, SEE SD-54104-083
- 梱包数量：1500個/リール
NUMBER OF CONNECTORS：1500PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH
20PCS. MIN. トップテープ接着部 (空エンボス)
TOP TAPE BONDED PART. (EMPTY)
部品挿入部
COMPONENT
SUPPLIER
末端部
(空部)
TAIL PART
(EMPTY)
400 MIN. 40 MIN.
- トップテープの剥離強度については、IEC60286-3に準拠
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.
- 材料
キャリアテープ：ポリプロピレン
トップテープ：PET, PE, PEF
リール：ポリスチレン (PE) <リサイクル材を含む>
MATERIAL
CARRIERTAPE：POLYPROPYLENE
TOPTAPE：PET, PE, PEF
REEL：POLYSTYREN (PE) <RECYCLE MATERIAL CONTAINED>
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



RELEASED EC NO: J2013-1003 DRWN:KNAGUMO 2012/09/05 CH'KD:KTAKAHASHI 2012/09/06 APPR:KMORIKAWA 2013/03/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY KNAGUMO	DATE 2012/09/05	TITLE EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF R/A HOUSING ASSY molex				
		10 OVER 30 UNDER	± ---	CHECKED BY KTAKAHASHI	DATE 2012/09/06					
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2013/03/15					
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.			SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54104-084			1 OF 2		
	REV 0	SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

